# Advance Information 5 V Low-Drop Voltage Regulator

This industry standard linear regulator has the capability to drive loads up to 450 mA at 5 V. It is available in DPAK, D<sup>2</sup>PAK, and TO–220 options. This device is pin–for–pin compatible with Infineon part number TLE4275.

# Features

- 5 V, ±2%, 450 mA Output Voltage
- Very Low Current Consumption
- Active **RESET**
- Reset Low Down to  $V_0 = 1 V$
- 500 mV (max) Dropout Voltage
- Fault Protection
  - ◆ +45 V Peak Transient Voltage
  - ♦ -42 V Reverse Voltage
  - Short Circuit
  - Thermal Overload
- NCV Prefix for Automotive and Other Applications Requiring Site and Control Changes

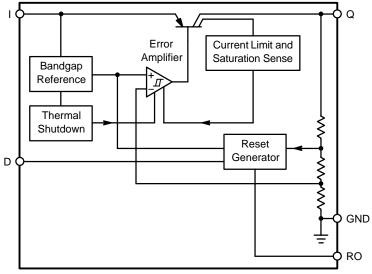


Figure 1. Block Diagram

This document contains information on a product under development. ON Semiconductor reserves the right to change or discontinue this product without notice.

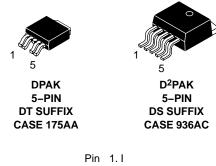
This document, and the information contained herein, is CONFIDENTIAL AND PROPRIETARY and the property of Semiconductor Components Industries, LLC., dba ON Semiconductor. It shall not be used, published, disclosed or disseminated outside of the Company, in whole or in part, without the written permission of ON Semiconductor. Reverse engineering of any or all of the information contained herein is strictly prohibited.

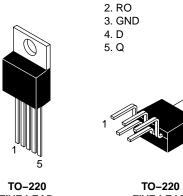
© 2004, SCILLC. All Rights Reserved.



# ON Semiconductor®

http://onsemi.com





FIVE LEAD T SUFFIX CASE 314D

FIVE LEAD TV SUFFIX CASE 314K

## **ORDERING INFORMATION**

Device	Package	Shipping
NCV4275DT	DPAK*	75 Units/Rail
NCV4275DTRK	DPAK*	2500 Tape & Reel
NCV4275DS	D <sup>2</sup> PAK*	50 Units/Rail
NCV4275DSR4	D <sup>2</sup> PAK*	750 Tape & Reel
NCV4275T	TO-220* STRAIGHT	50 Units/Rail
NCV4275TV	TO–220* BENT	50 Units/Rail

\*Five pin/lead.

## **DEVICE MARKING INFORMATION**

See general marking information in the device marking section on page 6 of this data sheet.

# **MAXIMUM RATINGS\*†**

Rating	Min	Max	Unit	
Input [I (DC)]			45	V
Input [I (Peak Transient Voltage)]		-	TBD	V
Output (Q)		-1.0	16	V
Reset Output (RO)		-0.3	25	V
Reset Output (RO)		-5.0	5.0	mA
Reset Delay (D)		-0.3	7.0	V
Reset Delay (D)		-2.0	2.0	mA
Operating Range (I)		5.5	42	V
ESD Susceptibility (Human Body Model)		2.0	-	kV
Junction Temperature		-40	150	°C
Storage Temperature		-55	150	°C
Package Thermal Resistance, DPAK, 5–Pin :	Junction–to–Case, $R_{\theta JC}$ Junction–to–Ambient, $R_{\theta JA}$	-	TBD TBD	°C/W °C/W
Package Thermal Resistance, D <sup>2</sup> PAK, 5–Pin :	Junction–to–Case, $R_{\theta JC}$ Junction–to–Ambient, $R_{\theta JA}$	-	TBD TBD	°C/W °C/W
Package Thermal Resistance, TO-220, 5-Lead:	Junction–to–Case, $R_{\theta JC}$ Junction–to–Ambient, $R_{\theta JA}$	-	TBD TBD	°C/W °C/W
Lead Temperature Soldering	Reflow (SMD styles only) Note 1	-	240 Peak	°C
w	-	(Note 3) 260 Peak	°C	

60 seconds max above 183°C.
 10 seconds max.

2. To seconds max.
3. -5°C/+0°C allowable conditions.
\*The maximum package power dissipation must be observed.
†During the voltage range which exceeds the maximum tested voltage of I, operation is assured, but not specified. Wider limits may apply. Thermal dissipation must be observed closely.

# $\label{eq:expectation} \textbf{ELECTRICAL CHARACTERISTICS} \quad (I = 13.5 \ \text{V}; -40^{\circ}\text{C} < \text{T}_J < 150^{\circ}\text{C}; \mbox{ unless otherwise noted})$

Characteristic	Test Conditions	Min	Тур	Max	Unit	
Output						
Output Voltage	$5.0 \text{ mA} < I_Q < 400 \text{ mA}, 6.0 \text{ V} < V_I < 28 \text{ V}$	4.9	5.0	5.1	V	
Output Voltage	$5.0 \text{ mA} < I_Q < 200 \text{ mA}, 6.0 \text{ V} < V_I < 40 \text{ V}$	4.9	5.0	5.1	V	
Output Current Limitation	-	450	700	-	mA	
Quiescent Current, $I_q = I_I - I_Q$	I <sub>Q</sub> = 1.0 mA	-	150	200	μΑ	
Quiescent Current, $I_q = I_I - I_Q$	I <sub>Q</sub> = 250 mA	-	10	15	mA	
Quiescent Current, $I_q = I_I - I_Q$	I <sub>Q</sub> = 400 mA	_	23	35	mA	
Dropout Voltage	$I_Q = 300 \text{ mA}, V_{dr} = V_I - V_Q$	-	250	500	mV	
Load Regulation	d Regulation $I_Q = 5.0 \text{ mA to } 400 \text{ mA}$		15	30	mV	
Line Regulation	$\Delta V = 8.0 \text{ V}$ to 32 V, I <sub>Q</sub> = 5.0 mA	-25	5.0	25	mV	
Power Supply Ripple Rejection	$f_r = 100 \text{ Hz}, V_r = 0.5 \text{ V}_{pp}$	-	60	-	dB	
Temperature Output Voltage Drift	age Drift –		0.5	-	mV/k	
Reset Timing D and Output RO						
Reset Switching Threshold –		4.5	4.65	4.8	V	
Reset Output Low Voltage	R <sub>ext</sub> > 5.0 k, V <sub>Q</sub> > 1.0 V	-	0.2	0.4	V	
Reset Output Leakage Current	V <sub>ROH</sub> = 5.0 V	-	0	10	μΑ	
Reset Charging Current	V <sub>D</sub> = 1.0 V	3.0	5.5	9.0	μΑ	
Upper Timing Threshold	-	1.5	1.8	2.2	V	
Lower Timing Threshold	-	0.2	0.4	0.7	V	
Reset Delay Time	C <sub>D</sub> = 47 nF	10	16	22	ms	
Reset Reaction Time	C <sub>D</sub> = 47 nF	-	1.5	4.0	μs	

# PIN DESCRIPTION

Pin No.	Symbol	Description		
1	I	Input; Battery Supply Input Voltage. Bypass to ground with a ceramic capacitor.		
2	RO	Reset Output; Open Collector Active Reset (accurate to I > 1.0 V).		
3	GND	Ground; Pin 3 internally connected to heatsink.		
4	D	Reset Delay; Connect to ground with a $\leq$ 22 $\mu$ F capacitor, ESR < 5 $\Omega$ at 10 kHz.		
5	Q	Output; ±2.0%, 450 mA output. Use 22 $\mu$ F, ESR < 5.0 $\Omega$ to ground.		

#### **APPLICATION INFORMATION**

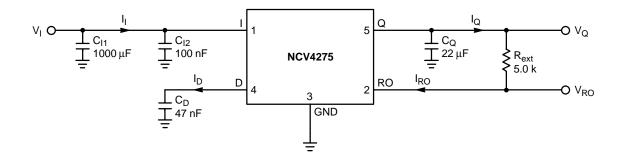


Figure 2. Test Circuit

#### **Circuit Description**

The error amplifier compares a temperature stable reference voltage to a voltage that is proportional to the output voltage (Q) (generated from a resistor divider) and drives the base of a series transistor via a buffer. Saturation control as a function of the load current prevents any oversaturation of the output power device preventing excessive substrate current (quiescent current).

Typical drop out voltage at 300 mA load is 250 mV, 500 mV maximum. Test voltage for drop out is 5 V input.

#### **Stability Considerations**

The input capacitors ( $C_{I1}$  and  $C_{I2}$ ) are necessary for line influences. Using a resistor of approximately 1  $\Omega$  in series with  $C_{I2}$  can solve potential oscillations due to stray inductance and capacitance.

The output or compensation capacitor helps determine three main characteristics of a linear regulator: start–up delay, load transient response and loop stability.

The capacitor value and type should be based on cost, availability, size and temperature constraints. A tantalum or aluminum electrolytic capacitor is best, since a film or ceramic capacitor with almost zero ESR can cause instability. The aluminum electrolytic capacitor is the least expensive solution, but, if the circuit operates at low temperatures ( $-25^{\circ}$ C to  $-40^{\circ}$ C), both the value and ESR of the capacitor will vary considerably. The capacitor manufacturers data sheet usually provides this information.

The value for the output capacitor  $C_{OUT}$  shown in Figure 2 should work for most applications, however it is not necessarily the optimized solution. Stability is guaranteed for  $C_Q > 22 \ \mu F$  and an ESR  $\leq 5 \ \Omega$ 

## Calculating Power Dissipation in a Single Output Linear Regulator

The maximum power dissipation for a single output regulator (Figure 3) is:

$$PD(max) = [VIN(max) - VOUT(min)] IOUT(max)$$
(1)  
+ VIN(max)Iq

where

V <sub>IN(max)</sub>	is the maximum input voltage,
V <sub>OUT(min)</sub>	is the minimum output voltage,
I <sub>OUT(max)</sub>	is the maximum output current for the
	application,
IQ	is the quiescent current the regulator
-	consumes at I <sub>OUT(max)</sub> .

Once the value of  $P_{D(max)}$  is known, the maximum permissible value of  $R_{\Theta JA}$  can be calculated:

$$R_{\Theta JA} = \frac{150^{\circ}C - T_A}{P_D}$$
(2)

The value of  $R_{\Theta JA}$  can then be compared with those in the package section of the data sheet. Those packages with  $R_{\Theta JA}$ 's less than the calculated value in Equation 2 will keep the die temperature below 150°C.

In some cases, none of the packages will be sufficient to dissipate the heat generated by the IC, and an external heatsink will be required.

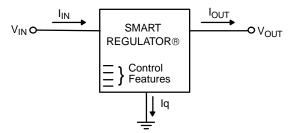


Figure 3. Single Output Regulator with Key Performance Parameters Labeled

# Heat Sinks

A heat sink effectively increases the surface area of the package to improve the flow of heat away from the IC and into the surrounding air.

Each material in the heat flow path between the IC and the outside environment will have a thermal resistance. Like series electrical resistances, these resistances are summed to determine the value of  $R_{\Theta JA}$ :

$$R_{\Theta}JA = R_{\Theta}JC + R_{\Theta}CS + R_{\Theta}SA \tag{3}$$

where

 $R_{\Theta JC}$  is the junction-to-case thermal resistance,

 $R_{\Theta CS}$  is the case-to-heatsink thermal resistance,

 $R_{\Theta SA}$  is the heatsink-to-ambient thermal resistance.

resistance.

 $R_{\Theta JC}$  appears in the package section of the data sheet. Like  $R_{\Theta JA}$ , it too is a function of package type.  $R_{\Theta CS}$  and  $R_{\Theta SA}$  are functions of the package type, heatsink and the interface between them. These values appear in heat sink data sheets of heat sink manufacturers.

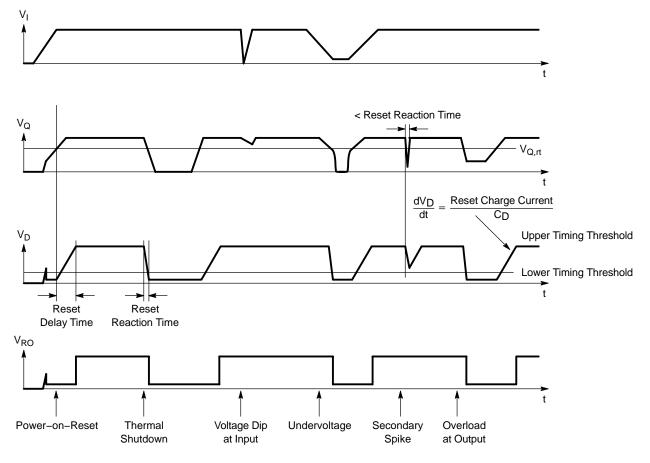
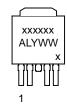


Figure 4. Reset Timing

## MARKING DIAGRAMS

DPAK DT SUFFIX CASE 175AA



D<sup>2</sup>PAK **DS SUFFIX** CASE 936AC

Ο

XXXXXXX AWLYYWW

1

TO-220 T SUFFIX CASE 314D





TO-220

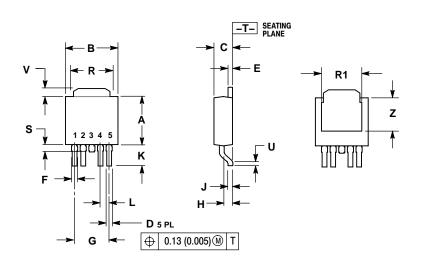
XX XXXXXXXXX AWLYWW 

XXX... = Specific Device Code

- А = Assembly Location
- WL, L = Wafer Lot
- YY, Y = Year
- WW, W = Work Week

# PACKAGE DIMENSIONS

**DPAK 5 CENTER LEAD CROP DT SUFFIX** CASE 175AA-01 ISSUE O



NOTES:

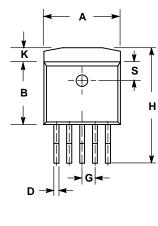
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982. 2.

CONTROLLING	DIMENSION:	INCH.

	INCHES		MILLIMETER	
DIM	MIN	MAX	MIN	MAX
Α	0.235	0.245	5.97	6.22
В	0.250	0.265	6.35	6.73
С	0.086	0.094	2.19	2.38
D	0.020	0.028	0.51	0.71
E	0.018	0.023	0.46	0.58
F	0.024	0.032	0.61	0.81
G	0.180	BSC	4.56 BSC	
н	0.034	0.040	0.87	1.01
J	0.018	0.023	0.46	0.58
к	0.102	0.114	2.60	2.89
L	0.045 BSC		1.14	BSC
R	0.170	0.190	4.32	4.83
R1	0.185	0.210	4.70	5.33
S	0.025	0.040	0.63	1.01
U	0.020		0.51	
v	0.035	0.050	0.89	1.27
Z	0.155	0.170	3.93	4.32

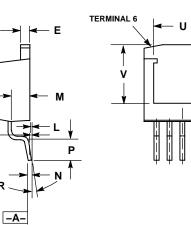
# PACKAGE DIMENSIONS

D<sup>2</sup>PAK 5 LEAD **DS SUFFIX** CASE 936AC-01 ISSUE O



w

R

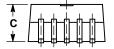


NOTES:

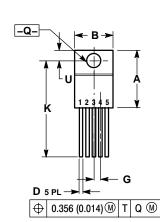
NOTES: 1. DIMENSIONS AND TOLERANCING PER ANSI Y14.5M, 1982. 2. CONTROLLING DIMENSION: INCH. 3. PACKAGE OUTLINE EXCLUSIVE OF MOLD FLASH AND METAL BURR. 4. PACKAGE OUTLINE INCLUSIVE OF PLATING THICKNESS. 5. EOOT LENCT HEASUBED AT

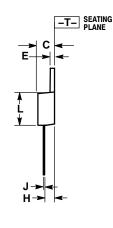
FOOT LENGTH MEASURED AT INTERCEPT POINT BETWEEN DATUM A AND LEAD SURFACE. 5.

	INC	HES	MILLIM	IETERS
DIM	MIN	MAX	MIN	MAX
Α	0.396	0.406	10.05	10.31
В	0.330	0.340	8.38	8.64
С	0.170	0.180	4.31	4.57
D	0.026	0.036	0.66	0.91
E	0.045	0.055	1.14	1.40
G	0.06	7 REF	1.70	) REF
н	0.580	0.620	14.73	15.75
ĸ	0.055	0.066	1.40	1.68
L	0.000	0.010	0.00	0.25
м	0.098	0.108	2.49	2.74
N	0.017	0.023	0.43	0.58
Р	0.090	0.110	2.29	2.79
R	0 °	8 °	0 °	8 °
S	0.095	0.105	2.41	2.67
U	0.30	0.30 REF 7.62 RE		2 REF
v	0.305 REF		7.75 REF	
w	0.0	10	0.25	



TO-220 **FIVE LEAD STRAIGHT T SUFFIX** CASE 314D-04 ISSUE E



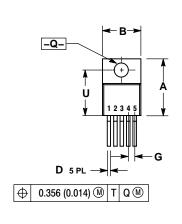


NOTES: 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982. 2. CONTROLLING DIMENSION: INCH. 3. DIMENSION D DOES NOT INCLUDE INTERCONNECT BAR (DAMBAR) PROTRUSION. DIMENSION D INCLUDING PROTRUSION SHALL NOT EXCEED 10.92 (0.043) MAXIMUM.

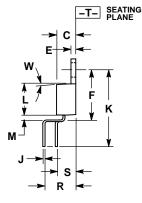
	INCHES		MILLIMETERS		
DIM	MIN	MAX	MIN	MAX	
Α	0.572	0.613	14.529	15.570	
В	0.390	0.415	9.906	10.541	
С	0.170	0.180	4.318	4.572	
D	0.025	0.038	0.635	0.965	
Е	0.048	0.055	1.219	1.397	
G	0.067	0.067 BSC		1.702 BSC	
Н	0.087	0.112	2.210	2.845	
J	0.015	0.025	0.381	0.635	
Κ	0.990	1.045	25.146	26.543	
L	0.320	0.365	8.128	9.271	
Q	0.140	0.153	3.556	3.886	
U	0.105	0.117	2.667	2.972	

#### PACKAGE DIMENSIONS

TO-220 **FIVE LEAD VERTICAL TV SUFFIX** CASE 314K-01 ISSUE O







NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M. 1982.

CONTROLLING DIMENSION: INCH

 DIMENSION D DOES NOT INCLUDE INTERCONNECT BAR (DAMBAR) PROTRUSION. DIMENSION D, INCLUDING PROTRUSION, SHALL NOT EXCEED 10.92 (0.043) MAXIMUM.

	INC	HES	MILLIMETERS	
DIM	MIN	MAX	MIN	MAX
Α	0.560	0.590	14.22	14.99
В	0.385	0.415	9.78	10.54
C	0.160	0.190	4.06	4.83
D	0.027	0.037	0.69	0.94
Е	0.045	0.055	1.14	1.40
F	0.530	0.545	13.46	13.84
G	0.067	' BSC	1.70	BSC
J	0.014	0.022	0.36	0.56
K	0.785	0.800	19.94	20.32
L	0.321	0.337	8.15	8.56
М	0.063	0.078	1.60	1.98
Q	0.146	0.156	3.71	3.96
R	0.271	0.321	6.88	8.15
S	0.146	0.196	3.71	4.98
U	0.460	0.475	11.68	12.07
W	5	5° 5°		0

ON Semiconductor and images without further notice components Industries, LLC (SCILLC). SCILLC reserves the right to make changes without further notice to any products herein. SCILLC makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does SCILLC assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. "Typical" parameters which may be provided in SCILLC data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. SCILLC does not convey any license under its patent rights nor the rights of others. SCILLC products are not designed, intended, or authorized for use as components in systems intended for surgical implant into the body, or other applications intended to support or sustain life, or for any other application in which the failure of the SCILLC product could create a situation where personal injury or death may occur. Should Buyer purchase or use SCILLC products for any such unintended or unauthorized application, Buyer shall indemnify and hold SCILLC and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use, even if such claim alleges that SCILLC was negligent regarding the design or manufacture of the part. SCILLC is an Equal Opportunity/Affirmative Action Employer. This literature is subject to all applicable copyright laws and is not for resale in any manner.

#### PUBLICATION ORDERING INFORMATION

#### LITERATURE FULFILLMENT

Literature Distribution Center for ON Semiconductor P.O. Box 5163, Denver, Colorado 80217 USA Phone: 303-675-2175 or 800-344-3860 Toll Free USA/Canada Fax: 303-675-2176 or 800-344-3867 Toll Free USA/Canada Email: orderlit@onsemi.com

N. American Technical Support: 800-282-9855 Toll Free USA/Canada

Japan: ON Semiconductor, Japan Customer Focus Center 2-9-1 Kamimeguro, Meguro-ku, Tokyo, Japan 153-0051 Phone: 81-3-5773-3850

ON Semiconductor Website: http://onsemi.com

Order Literature: http://www.onsemi.com/litorder

For additional information, please contact your local Sales Representative.